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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant: Choi et al.

Examiner: Zimmerman, John J.

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Filed: 2/15/2002

For: LEAD-FREE TIN-SILVER-COPPER ALLOY SOLDER COMPOSITION

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## **AMENDMENT**

Sir:

In supplementary response to the Final Office Action mailed February 11, 2004, please amend the above-identified application as follows: